

Attorney's Docket No.: 042390.P13563D

Patent

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:)
Youzhi E. Xu)
Application No: 10/781,314)
Filed: February 17, 2004)
For: IMPROVED HEAT TRANSFER)
THROUGH COVALENT BONDING)
OF THERMAL INTERFACE)
MATERIAL)

Examiner: Christopher Schatz

Art Unit: 1733

Mail Stop Amendment
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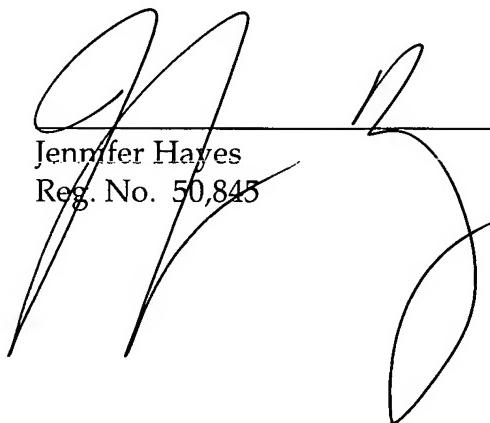
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Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: January 5, 2007

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(use as many sheets as necessary)

Sheet	2	of	2	Attorney Docket Number	042390.P13563D
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Complete if Known

Application Number	10/781,314
Filing Date	February 17, 2004
First Named Inventor:	Youzhi E. Xu
Art Unit	1733
Examiner Name	Christopher Schatz

NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ²
		MIRNGH-JI LII, ET AL.; Flip-Chip Technology on Organic Pin Grid Array Packages; Intel Technology Journal Q3, 2000, pp. 1-9.	
		RAVI MAHAJAN, ET AL.; The Evolution of Microprocessor Packaging; Intel Technology Journal Q3, 2000; pp. 1-10.	
		THOMAS E. BROWNE, ET AL.; Polymer-Grafted Silica: A Screening System for Polymeric Absorption Resin Development; I&EC Research, 1993, 32, American Chemical Society; p. 6.	
		PATRIC JINNASCH; Preparation and studies of ion conduction molecular composites; http://www.polymer.lth.se/Students/MastersTheseList/MT03/ ; Downloaded December 4, 2001; 2 pages.	
		THOMAS OLLILA; Selection Criteria for Thermal Interface Materials; http://chomerics.com/tech/therm_mgmt_artcls/TIMarticle.pdf ; 4 pages.	
		[Report]Polymer Nanocomposites: Introduction: Objective and Purpose of this Report; http://www.the-infoshop.com/study/bc5502_polymer_nanocomposites.html ; Downloaded December 10, 2001; 1 page.	
		Physical Constants of IC Package Materials; 2000 Packaging Databook; http://www.developer.intel.com/design/packtech/ch_05.pdf ; pp. 5-1 thru 5-4.	
		RAM VISWANATH, ET AL.; Thermal Performance Challenges from Silicon to Systems; Intel Technology Journal Q3, 2000; pp. 1-16.	
		Y.E. XU, ET AL.; Development and Certification of a Thermal Interface Material for Mobile Coppermine and Cascade 256K Cartridge Packages; Intel Assembly & Test Technology Journal; 1999; Vol. 2; pp.1-5.	

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